

Dual IF Receivers with SNRBoost^{3G+} Signal Processing

Check for Samples: [ADS58C20](#) , [ADS58C23](#)

FEATURES

- Differential Analog IF Input, DDR LVDS Digital IF Output
- Up to 125-MHz Signal Bandwidth per Receiver
 - With 40- and 75-MHz optimized bands
- High Dynamic Performance
- High Impedance Input
- 80-Pin TQFP Package with PowerPAD™

APPLICATIONS

- **ADS58C20: Multi-Carrier GSM/3G/LTE/TDS-CDMA Cellular Base-station Receiver**
- **ADS58C23: Multi-Carrier 3G/LTE/TDS-CDMA Cellular Base-station Receiver**

DESCRIPTION

The ADS58C20 and ADS58C23 are dual IF receivers for wideband, multi-mode cellular infrastructure base stations. Each channel provides high dynamic performance up to 125 MHz of bandwidth, with optimized bands of 40- and 75-MHz. The IF receiver architecture eases front end filter design for wide bandwidth receivers. The receivers have integrated buffers at the analog inputs with benefits of uniform performance and input impedance across a wide frequency range.

The ADS58C20 is a high performance part with superior specifications for single/multi-mode cellular base-station receivers that include multi-carrier GSM. It can also process other cellular protocols such as TDS-CDMA/3G/LTE and prior generation systems.

The ADS58C23 offers the same functionality and pinout as ADS58C20 but with reduced minimum performance specifications for lower cost and performance systems, such as TDS-CDMA/3G/LTE single/multi-mode receivers (when GSM is not required). It can also process prior generation protocols.

The devices are available in a 80-pin TQFP package, and are specified over the full industrial temperature range (–40°C to 85°C).



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
ADS58C20IPFP	ACTIVE	HTQFP	PFP	80	96	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	ADS58C20I	Samples
ADS58C20IPFPR	ACTIVE	HTQFP	PFP	80	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	ADS58C20I	Samples
ADS58C23IPFP	ACTIVE	HTQFP	PFP	80	96	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	ADS58C23I	Samples
ADS58C23IPFPR	ACTIVE	HTQFP	PFP	80	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	ADS58C23I	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

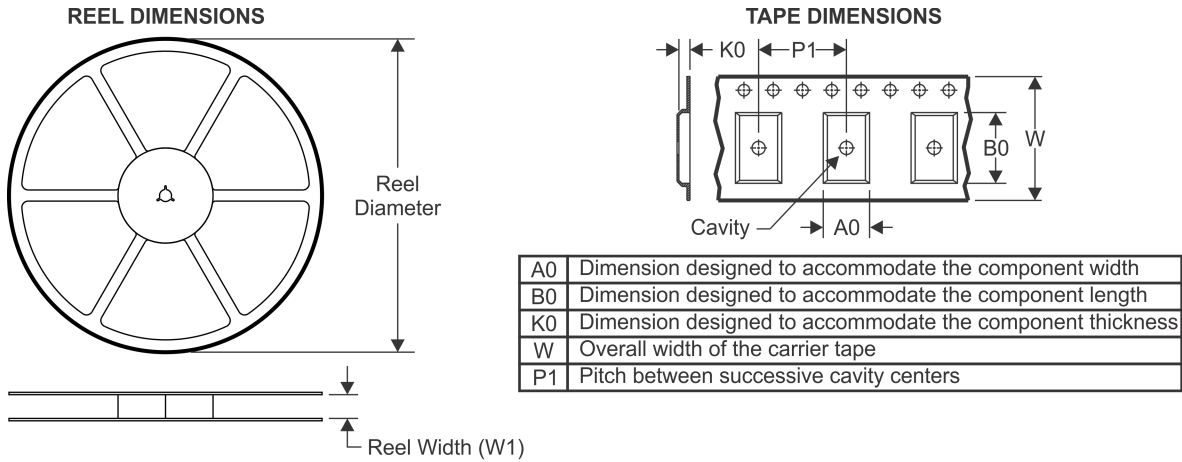
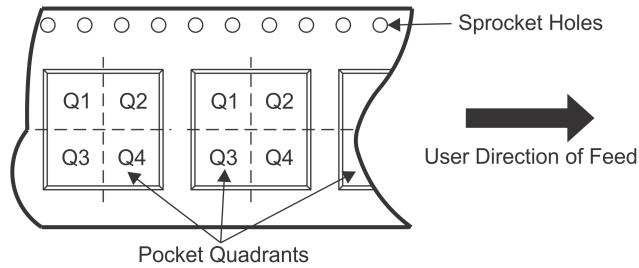
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ADS58C20IPFPR	HTQFP	PFP	80	1000	330.0	24.4	15.0	15.0	1.5	20.0	24.0	Q2
ADS58C23IPFPR	HTQFP	PFP	80	1000	330.0	24.4	15.0	15.0	1.5	20.0	24.0	Q2

TAPE AND REEL BOX DIMENSIONS

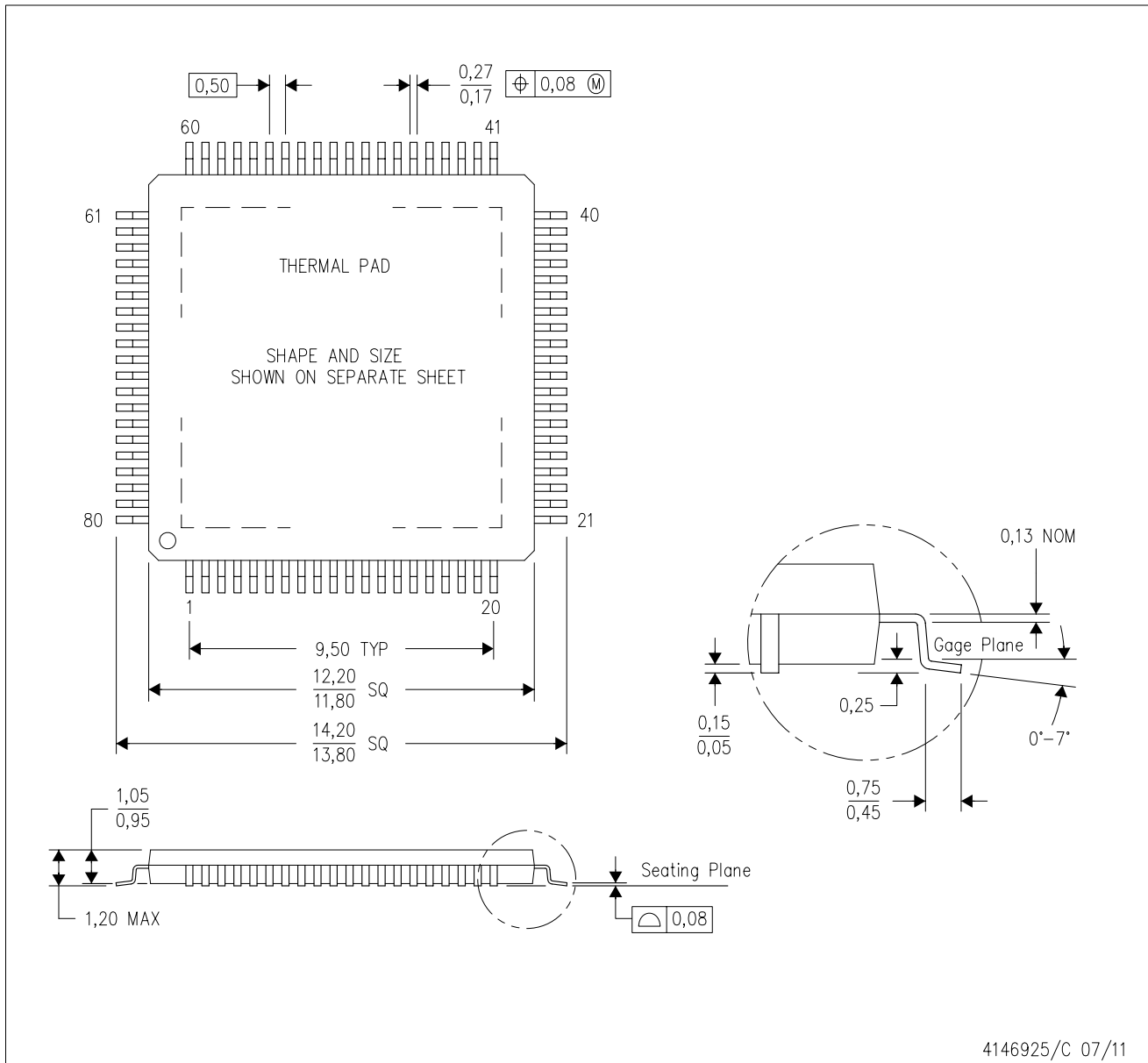

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ADS58C20IPFPR	HTQFP	PFP	80	1000	367.0	367.0	45.0
ADS58C23IPFPR	HTQFP	PFP	80	1000	367.0	367.0	45.0

MECHANICAL DATA

PFP (S-PQFP-G80)

PowerPAD™ PLASTIC QUAD FLATPACK



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- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <<http://www.ti.com>>.
 - E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - F. Falls within JEDEC MS-026

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THERMAL PAD MECHANICAL DATA

PFP (S-PQFP-G80)

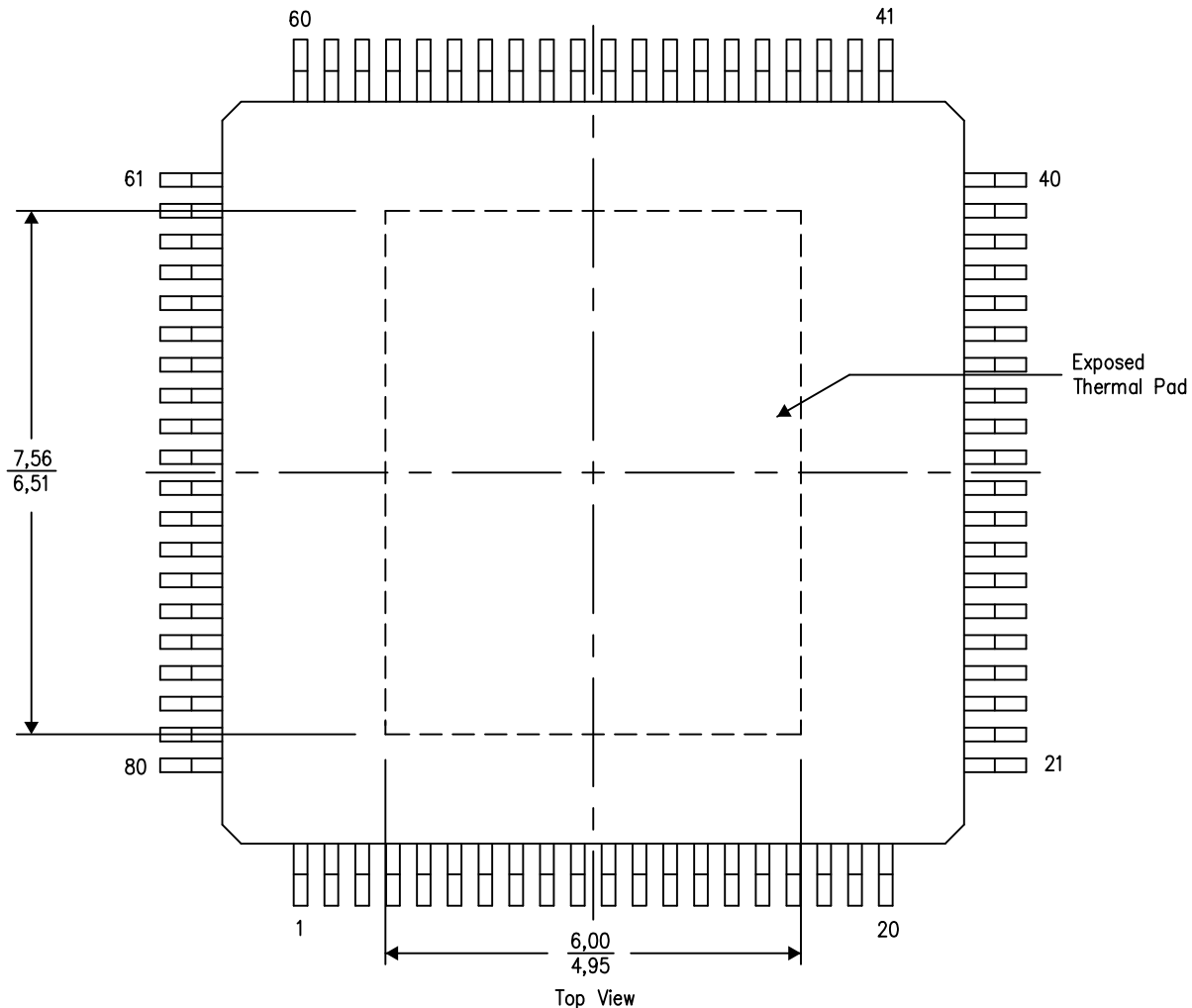
PowerPAD™ PLASTIC QUAD FLATPACK

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



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NOTE: A. All linear dimensions are in millimeters

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